C205 Broadband plasma optical patterned wafer inspection system discovers defects that affect the yield and reliability of semiconductor chips

**Benefits:**
The C205 provides high sensitivity discovery and binning of critical defects, helping automotive chipmakers:
- Accelerate R&D and ramp cycle time through characterization and optimization of new processes, design nodes and devices
- Implement defect reduction strategies to meet chip quality requirements
- Reduce die overkill by providing accurate, actionable data on reliability-related defects
- Detect and characterize sub-design rule defects that can become latent defect escapes

**Technologies:**
- Tunable DUV, UV, visible broadband illumination source
- Selectable optical apertures
- Low-noise sensor
- NanoPoint™ technology
- Advanced defect detection algorithms
- Automated defect binning

**Applications:**
- Systematic defect discovery for R&D and ramp
- Process window qualification
- Process change verification for continuous improvement
- Inline monitoring of critical layers requiring high sensitivity

**Markets:**
Chip manufacturing
larger design node devices for automotive, IoT, 5G, consumer electronics, industrial (military, aerospace, medical)

**Platform:**
- Customizable configurations
- Extendible
- Upgradeable

**Wafer Sizes:**
- 300mm
- 200mm

**More Information:**
www.kla.com/products/chip-manufacturing/defect-inspection-review#product-c205